# LINEAR TECHNOLOGY MATERIALS DECLARATION

**lt3060ets8-1.8#trmpbf** **(Engineering Calculation)** **TSOT-23**

**(printed on: 2020-07-11 18:10:50)** **TOTAL MASS (g): 0.01256**

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. |
|---|---|---|---|---|---|---|
| **Active Device** | Linear Technology | Silicon (Si) | 7440-21-3 | **0.000523** | **1000000** | **41641.15625** |
| **Die Coat** | Dow Corning | Silicone | 69430-27-9 | **0.000000** | **0** | **0** |
| **Lead Frame** | Cu | Copper (Cu) | 7440-50-8 | 0.004582 | 975000 | 364817.90625 |
| | | Iron (Fe) | 7439-89-6 | 0.000113 | 24000 | 8997.03710938 |
| | | Phosphorus (P) | 7723-14-0 | 0.000001 | 300 | 79.6197891235 |
| | | Zinc (Zn) | 7440-66-6 | 0.000003 | 700 | 238.859405518 |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 |
| | | **Lead Frame Total:** | | **0.004699** | **1000000** | **374133.4375** |
| **Plating** | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 |
| | | Exter. Plating Sn | 7440-31-5 | 0.000663 | 1000000 | 52763.2421875 |
| | | **External Plating Total:** | | **0.000663** | **1000000** | **52763.2421875** |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 |
| | | Inter. Plating Ag | 7440-22-4 | 0.000080 | 1000000 | 6369.58398438 |
| | | **Internal Plating Total:** | | **0.000080** | **1000000** | **6369.58398438** |
| **Die Attach** | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000395 | 750000 | 31449.8203125 |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 |
| | | Metal Oxide | | 0.000000 | 0 | 0 |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 |
| | | Resin (EP) | | 0.000132 | 250000 | 10509.8134766 |
| | | **Die Attach Total:** | | **0.000527** | **1000000** | **41959.6328125** |
| **Encapsulation** | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.000777 | 130000 | 61864.5820312 |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 |
| | | Silica (SiO2) | 60676-86-0 | 0.004963 | 830000 | 395153.03125 |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 |
| | | Metal Hydroxide | | 0.000209 | 35000 | 16640.5390625 |
| | | Carbon Black (C) | 1333-86-4 | 0.000030 | 5000 | 2388.59375 |
| | | **Encapsulation Total:** | | **0.005979** | **1000000** | **476046.78125** |
| **Bond Wire Estimated** | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | **0.000089** | **1000000** | **7086.16210938** |
| | | | | | **TOTAL MASS (g):** | **0.01256** |